

# SOT1180-1

plastic thermal enhanced very very thin quad flat package;  
no leads; 32 terminals

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HWQFN32
<b>Package type industry code</b>	HWQFN32
<b>Package style descriptive code</b>	HWQFN (thermal enhanced very very thin quad flatpack; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	---
<b>JEDEC package outline code</b>	---
<b>JEITA package outline code</b>	---
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	5-8-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.9	-	3	3.1	mm
E	package width	5.9	-	6	6.1	mm
A	seated height	0.7	-	0.75	0.8	mm
e	nominal pitch	-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	32	-	

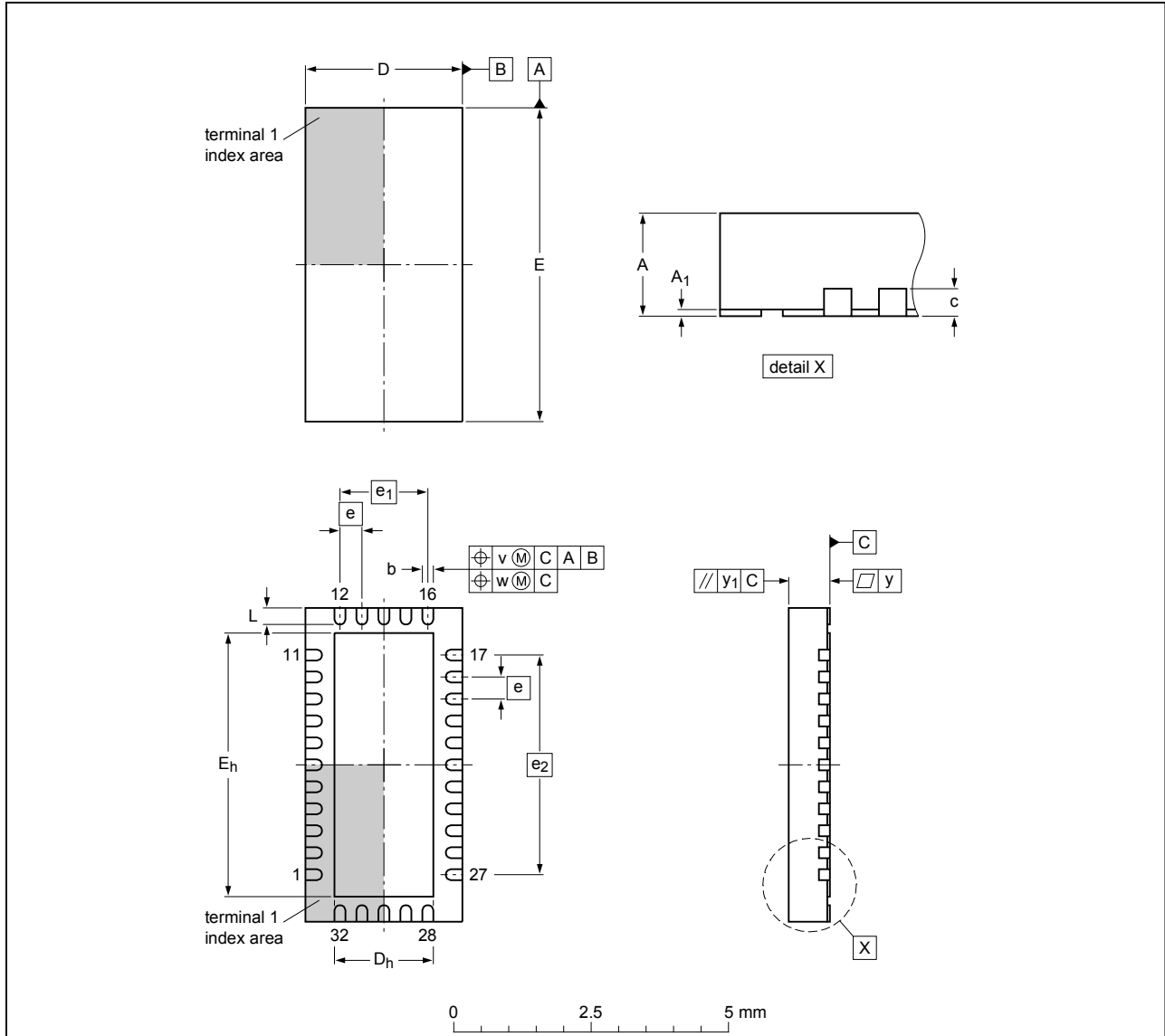


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## 2. Package outline

HWQFN32: plastic thermal enhanced very very thin quad flat package; no leads; 32 terminals; 3 x 6 x 0.75 mm

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Dimensions

Unit	A <sup>(1)</sup>	A <sub>1</sub>	b	c	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(1)</sup>	E <sub>h</sub>	e	e <sub>1</sub>	e <sub>2</sub>	L	v	w	y	y <sub>1</sub>
mm	max 0.80	0.05	0.25		3.1	1.9	6.1	4.9				0.4				
	nom 0.75	0.02	0.20	0.2	3.0	1.8	6.0	4.8	0.4	1.6	4	0.3	0.07	0.05	0.08	0.1
	min 0.70	0.00	0.15		2.9	1.7	5.9	4.7				0.2				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1180-1	---	---	---		10-07-02 10-08-05

Fig. 1. Package outline HWQFN32 (SOT1180-1)

### 3. Legal information

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